### 502118097 11/06/2012

#### PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Haizhou Yin	11/05/2012
Zhijiong Luo	11/05/2012
Huilong Zhu	11/05/2012
Da Yang	11/05/2012

#### RECEIVING PARTY DATA

Name:	The Institute of Microelectronics, Chinese Academy of Science
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## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13696308

#### CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 111695HK\_120913\_115

NAME OF SUBMITTER: Qing Ye

Total Attachments: 4

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> PATENT REEL: 029243 FRAME: 0830

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Docket No. 111695HK.120913.115 "Assignment Signature Page" Method of Manufacturing a Semiconductor Device

# **ASSIGNMENT**

WHEREAS I/We, the below named inventor(s),

Haizhou YIN	of	Poukeepsie, NY
Zhijiong LUO	of	Poukeepsie, NY
Huilong ZHU	of	Poukeepsie, NY
Da YANG	of	Beijing, China

hereby sell and assign to The Institute of Microelectronics, Chinese Academy of Sciences, a corporation of P.R.China, whose post office address is 3 Beitucheng West Road, Chaoyang District, Beijing 100029, P.R.China, hereinafter referred to as "Company", its successors and assigns our entire respective rights, titles and interests in and to the invention and improvements invented and originated by us and described in the Chinese Patent Application No. 201110155636.X filed on June 10, 2011 and PCT international Application Number PCT/2012/000670 filed on May 16, 2012 and for United States Patent currently entitled:

Method of Manufacturing a Semiconductor Device Executed concurrently herewith,

and any and all applications for patent and patents therefrom in any and all countries, including all divisions, continuations, reexaminations and reissues thereof, and all rights of priority resulting from the filing of said United States application, and authorize and request any official whose duty it is to issue patents, to issue any patent on said inventions and improvements resulting therefrom to said Company, or its successors or assigns and agree that on request and without further consideration, but at the expense of said Company, we will communicate to said Company or its representatives or nominees any facts known to us respecting said inventions and improvements and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, reexamination and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention and its improvements in all countries.

AND We/I hereby authorize and request our/my agents, USPTO customer number 93229, whose address is 106 Oakland PI, Los Gatos, CA 95032, to insert hereon any identification necessary or desirable for recordation of this document, including the filing date and application number of said application when known.

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AND We/I hereby covenant for ourselves/myself and our/my legal representatives, and agree with said Company, its successors and assigns, that We/I have granted no right or license to make, use, sell or offer to sell said improvements, to anyone except said Company, that prior to the execution of this assignment document, our/my right, title and interest in said improvements had not been otherwise encumbered, and that We/I have not and will not execute any instrument in conflict therewith;

AND We/I do hereby authorize and request the Director of the United States Patent and Trademark Office to issue any and all letters patent which may be granted upon said United States applications, or upon said improvements or any parts thereof when granted, to said Company.

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PATENT REEL: 029243 FRAME: 0832

Docket No. 111695HK.120913.115 "Assignment Method of Manufacturing a Semiconductor Dev	ent Signaturice	re Page"	
INVENTOR 1			
Signature: Haizhou YIN	Date:	11/5/212	
Witnessed by: Fon Young Signature	Date: _	11/5/0012	
Printed Name of Witness			
Witnessed by: XTANN HAN Signature	Date: _	11/5/2012	
Printed Name of Witness			
INVENTOR 2			
Signature: Zhijiong Luci	Date: _	11/5/2012	
Witnessed by: For Vorna Signature	Date: _	11/5/00/2	
Printed Name of Witness			
Witnessed by: X (av W HAV Signature	Date; _	11/5/2012	
Printed Name of Militage			

REEL: 029243 FRAME: 0833

Docket No. 111695HK.120913.115 "Assign Method of Manufacturing a Semiconductor D	ment Signature Page" levice
INVENTOR 3	:
Signature: Huilong ZHU Witnessed by: Signature	Date:
Printed Name of Witness	
Witnessed by: X(wW HAN Signature X(asW HAN Printed Name of Witness	Date: 11/5/ 12
Printed Name of Witness	
·	
Signature: Dayag Da YANG	Date:
Witnessed by: Fan Yang Signature	Date: <u>V//5 / do/2</u>
Printed Name of Witness	
Witnessed by: XIaw W HAN Signature	Date: 11/5/2012
XIAO W HAN	
Printed Name of Witness	

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